I.   AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.   (Currently Amended) A semiconductor futures exchange system comprising:

a virtual semiconductor fabrication facility (virtual fab) which provides information regarding fabrication of semiconductor devices, the virtual fab comprising at least one communications interface with a semiconductor foundry and a plurality of manufacturing capacity contracts, wherein the virtual fab further comprises a work in progress (WIP) reporting system for the virtual semiconductor fabrication facility; and

a semiconductor futures exchange coupled to the virtual fab adapted to trade semiconductor manufacturing capacity futures based on the plurality of manufacturing capacity contracts and a reported WIP.

2-5.   Canceled

6.   (Previously presented) The semiconductor futures exchange system of claim 1 further comprising at least one entity adapted for communicating between a computer system associated with the semiconductor futures exchange and a computer system associated with the virtual semiconductor fabrication facility.

7.   (Previously presented) The semiconductor futures exchange system of claim 1 further comprising a manufacturing executing system used to facilitate production in the virtual semiconductor fabrication facility.

8.   (Previously presented) The semiconductor futures exchange system of claim 1 further comprising at least one entity associated with a specific process within the virtual semiconductor fabrication facility.

9.   (Previously presented) The semiconductor futures exchange system of claim 1 further comprising at least one entity adapted for communicating between a computer system associated with an external service provider and a computer system associated with the semiconductor futures exchange.

10.   (Previously presented) The semiconductor futures exchange system of claim 9, wherein the computer system associated with the semiconductor futures exchange is adapted to be accessed by an investor.

11.   (Previously presented) The semiconductor futures exchange system of claim 9, wherein the computer system associated with the semiconductor futures exchange is adapted to be accessed by is a customer.

12.   (Previously presented) The semiconductor futures exchange system of claim 9, wherein the computer system associated with the semiconductor futures exchange is adapted to be accessed by a trader.

13.   (Previously presented) The semiconductor futures exchange system of claim 1, wherein the virtual semiconductor fabrication facility performs a plurality of processes associated with semiconductor fabrication.

14.   Canceled

15.   (Previously presented) The semiconductor futures exchange system of claim 1 wherein the semiconductor futures exchange is adapted to interact with a plurality of traders.

16.   (Currently Amended) A method of exchanging semiconductor futures comprising:
        providing a semiconductor futures exchange;
        coupling the semiconductor futures exchange to a virtual fab, wherein the virtual fab comprises at least one communications interface with a semiconductor foundry, [[and]] a plurality of manufacturing capacity contracts, and a work in progress [WIP] reporting system; and
        interacting with the semiconductor futures exchange through the virtual fab to trade semiconductor manufacturing capacity futures based on the plurality of manufacturing capacity [[capacity]] contracts and a reported WIP.
17-18. Canceled

19.   (Previously presented) The method of claim 16 wherein the semiconductor futures exchange is adapted to interact with a customer.

20.   (Previously presented) The method of claim 16 wherein the semiconductor futures exchange is adapted to interact with an investor.

21.   (Previously presented) The method of claim 16 wherein the semiconductor futures exchange is adapted to interact with a trader.

22.   (Previously presented) The method of claim 16 wherein the virtual fab includes a plurality of entities.

23.   (Previously presented) The method of claim 16 wherein the semiconductor futures exchange interfaces via the virtual fab with entities internal to and external to the virtual fab.

24.   Canceled

25.   (Previously presented) The method of claim 16 wherein the semiconductor capacity futures exchange includes a trade processor for executing trades of the semiconductor manufacturing capacity futures through a market established by the semiconductor futures exchange.